



Toshiba's SO6L Package IC Photocoplers Now Have Option for Wide Leadform

New products realise direct replacement from current SDIP6(F type) package products.

Düsseldorf, Germany, 28 September, 2017 – Toshiba Electronics Europe is expanding its line-up of SO6L IC photocoplers with a new wide leadform package type SO6L(LF4). The wide leadform option is available for three high-speed IC photocoplers and five IGBT/MOSFET driver photocoplers.

The new photocoplers can be directly mounted on PCB pads intended for SDIP6(F type) products. The SO6L(LF4)'s 2.3mm (max.) low profile package offers a 45% height reduction over SDIP6(F Type) and allows use in height-critical applications, such as mounting on the underside of PCBs.

The SO6L(LF4) package has a pin spacing of 9.35mm (min.) giving a safety creepage distance of 8.0mm and a BVs of 5kVrms (min.).

To support the replacement of more popular SDIP6(F type) package products, Toshiba will expand the wide leadform option to include other SO6L IC photocoplers.

The new devices are ideal for use in a wide range of applications including high-speed digital interfacing, I/O interfaces, PLCs, intelligent power modules and inverters for air conditioning, industrial applications and solar energy.

Mass production of the SO6L IC photocouplers has commenced.

Notes:

The latest Gartner market report recognizes Toshiba as the leading manufacturer of optocouplers by sales in 2015 and 2016, with 23% of sale-based market share in CY2016. (Source: Gartner "Market Share: Semiconductor Devices and Applications Worldwide 2016" 30 March, 2016)

Toshiba will continue to deliver products that meet the needs of customers by promoting the development of a diverse portfolio of photocouplers and photorelays tailored to market trends.

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About Toshiba Electronics Europe

[Toshiba Electronics Europe](#) (TEE) is the European electronic components business of [Toshiba Electronic Devices and Storage Corporation](#). TEE offers a broad IC and discrete product line including high-end memory, microcontrollers, ASICs and ASSPs for automotive, multimedia, industrial, telecoms and networking applications. The company also has a wide range of power semiconductor solutions as well as storage products including HDDs, SSDs, SD Cards and USB sticks.

TEE was formed in 1973 in Neuss, Germany, providing design, manufacturing, marketing and sales and now has headquarters in Düsseldorf, Germany, with branch offices in France, Italy, Spain, Sweden and the United Kingdom. TEE employs approximately 300 people in Europe. Company president is Mr Akira Morinaga. For more company information visit TEE's web site at www.toshiba.semicon-storage.com.

Contact details for publication:

Toshiba Electronics Europe GmbH, Hansaallee 181, D-40549 Düsseldorf, Germany

Tel: +49 (0) 211 5296 0 Fax: +49 (0) 211 5296 79197

Web: www.toshiba.semicon-storage.com/eu/company/news.html

E-mail: discrete-ic@toshiba-components.com

Contact details for editorial enquiries:

Michelle Shrimpton, Toshiba Electronics Europe GmbH

Tel: +44 (0)193 282 2832

E-mail: MShrimpton@teu.toshiba.de

Issued by:

Birgit Schöniger, Publitek

Tel: +44 (0) 20 8429 6554

Web: www.publitek.com

E-mail: birgit.schoeniger@publitek.com

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